

ABSTRACT

The invention provides conductive resin compositions which may be B-staged (semi-cured) at a relatively low temperature to exhibit sufficient tack-free properties and
5 excellent pressure-sensitive tackiness permitting temporary bonding of parts without involving solvent evaporation or light illumination, thereby suppressing an increase in facility costs, and which may be thereafter cured (C-staged) to give cured products having sufficient bond strength while maintaining low specific resistivity. The invention also provides cured products of the compositions. The conductive resin
10 composition includes an epoxy resin (A), a compound (B) having a (meth)acryloyl group and a glycidyl group, a phenolic resin curing agent (C), a radical polymerization initiator (D) and a conductive particle (E). The cured product is obtained from the composition.